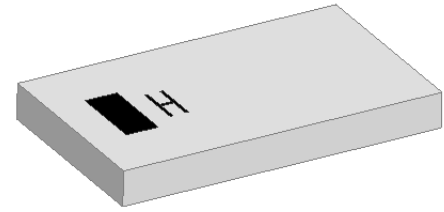


UWB 8060 Chip Antenna: ANT8060R55001KM1

Application:

UWB indoor location, Smart Key, etc...



Features

SMD, high reliability, ultra compact, Omni-directional...

Part number

ANT 8060 R 5500 1K M1
 (1) (2) (3) (4) (5)

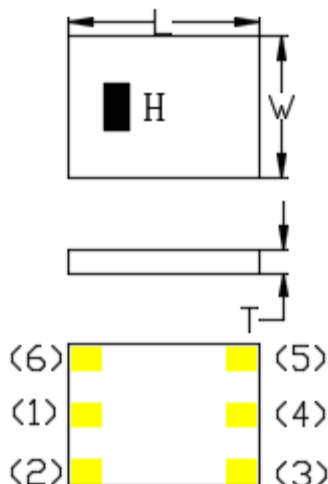
| | |
|--------------------|---------------|
| (1) Size Code | 8.0x6.0mm |
| (2) Packing | Tape and reel |
| (3) Frequency | 5500MHz |
| (4) Packing Number | 1K |
| (5) Code | M1 |

Electrical Specification

| | |
|---------------------------|------------------|
| Working Frequency Range | 3500~8500 MHz |
| Peak Gain | 3.5 dBi (Typ.) |
| Impedance | 50 Ohm |
| VSWR | 3.0 (Max) |
| Polarization | Linear |
| Azimuth Beamwidth | Omni-directional |
| Operation Temperature(°C) | -40 ~85°C |

The specification is defined on HEK EVB.

Dimension and Terminal Configuration



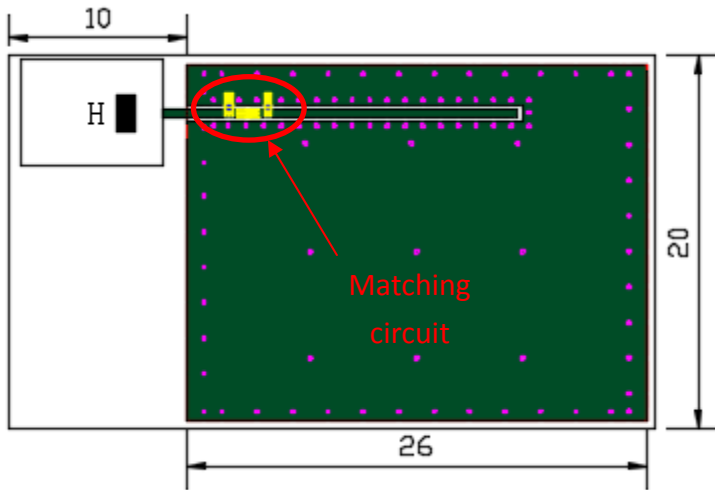
| Dimension (mm) | |
|----------------|----------|
| L | 8.0±0.15 |
| W | 6.0±0.15 |
| T | 1.0±0.10 |

| No. | Terminal Name |
|-----------|---------------|
| 1 | Feeding |
| 2,3,4,5,6 | Soldering |

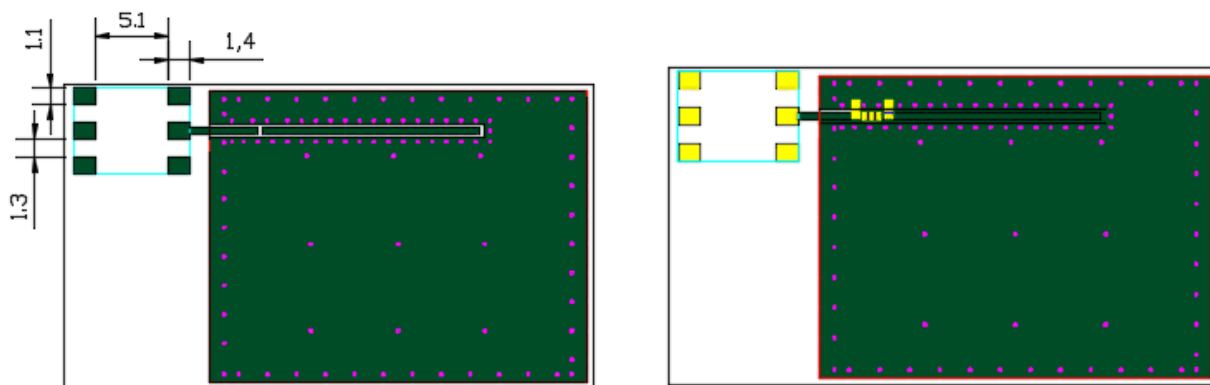
UWB 8060 Chip Antenna: ANT8060R55001KM1

Evaluation Board Reference


PCB Dimension




Antenna Layout Reference



Unit : mm

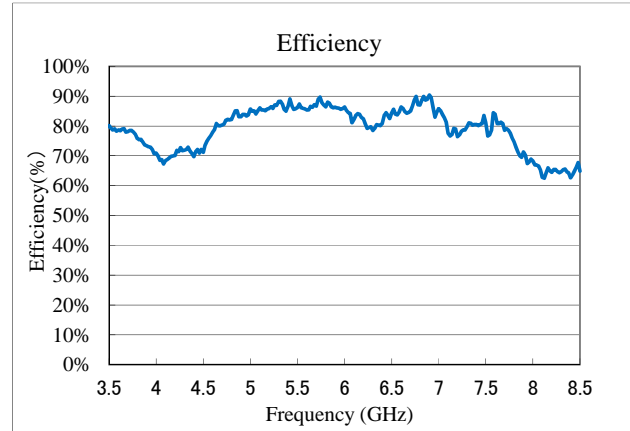
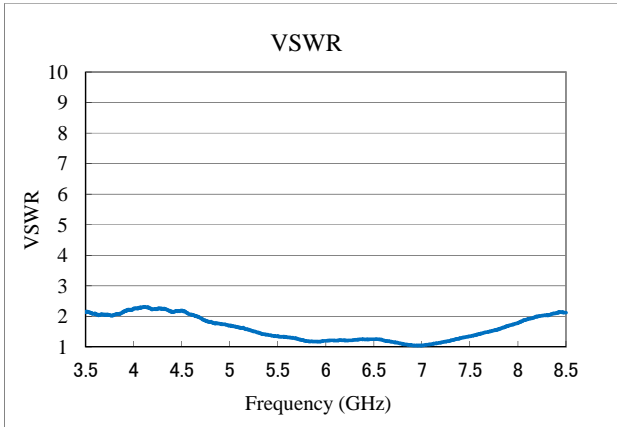
 : Chip Antenna

 : Land Pattern

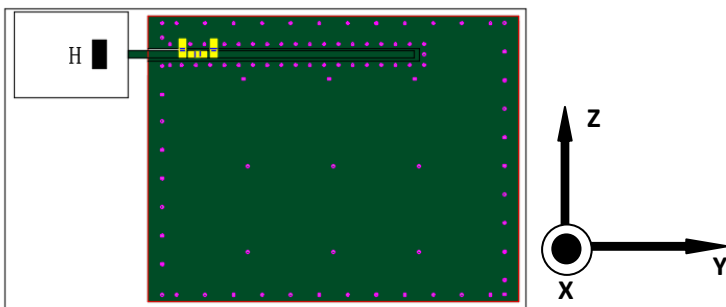
Electrical Characteristics

Return Loss & Radiation

VSWR&Efficiency

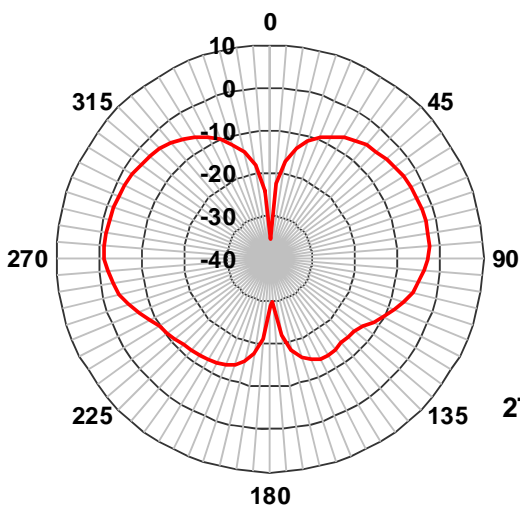


Radiation Pattern

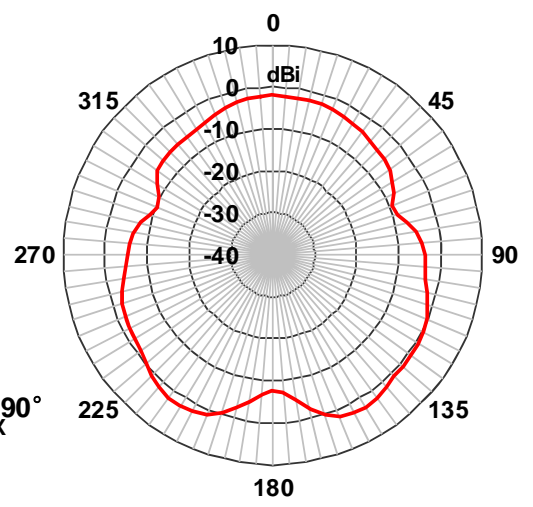


Frequency=5500MHz

ZX-Plane



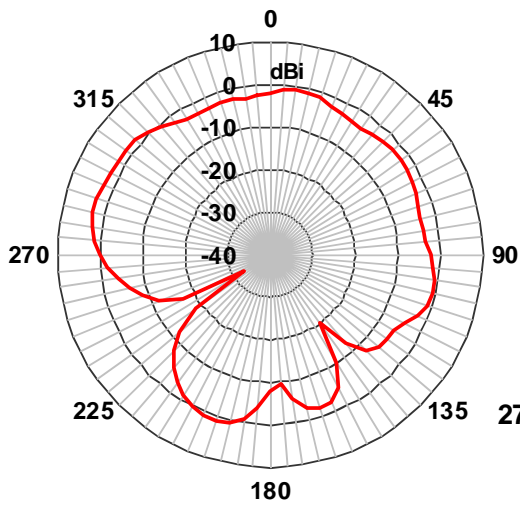
Horizontal Polarization



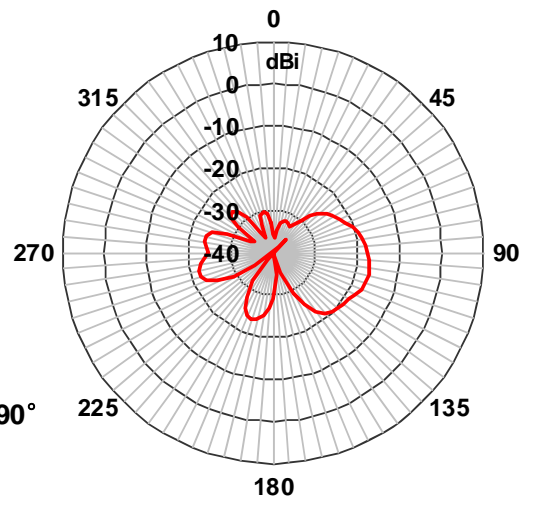
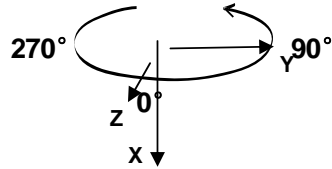
Vertical Polarization

ZY-Plane

UWB 8060 Chip Antenna: ANT8060R55001KM1

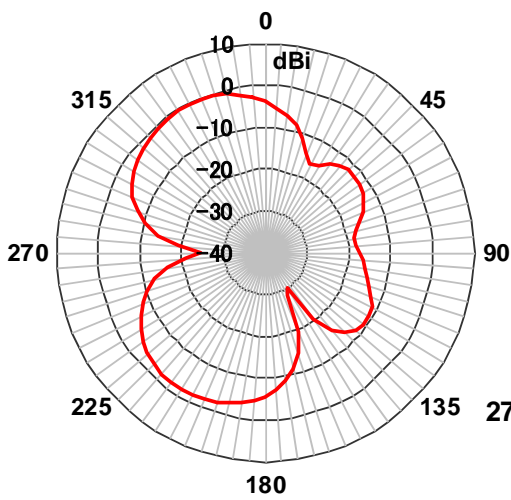


Horizontal Polarization

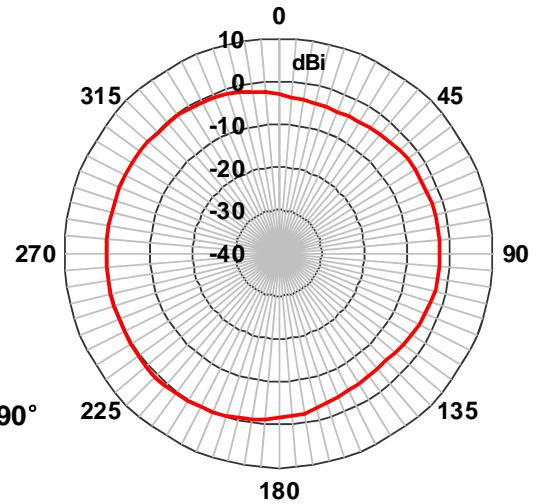
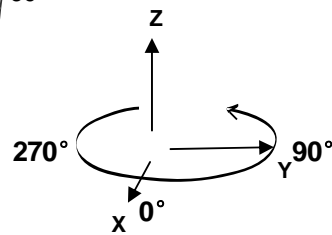


Vertical Polarization

XY-Plane



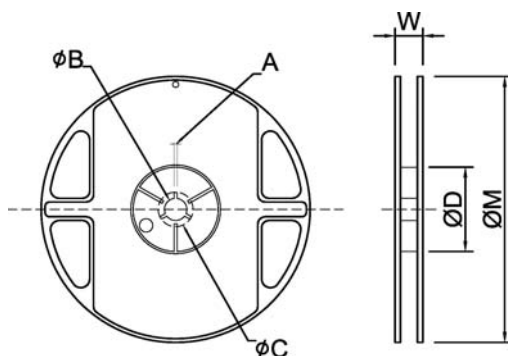
Horizontal Polarization



Vertical Polarization

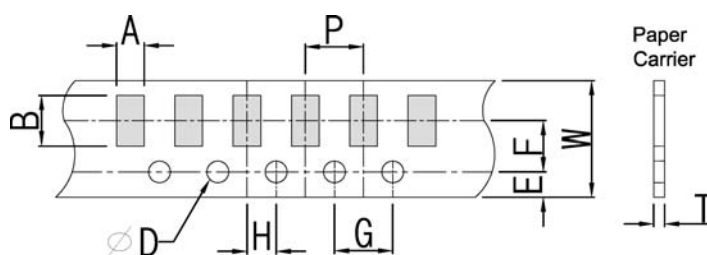
Reel and Taping Specification

Reel Specification



| TYPE | SIZE | A | ϕB | ϕC | ϕD | W | ϕM |
|------|-------------|---------|----------|----------|----------|----------|----------|
| 8060 | 13" 1K/Reel | 2.0±0.5 | 13.0±1.0 | 21±1.0 | 67±1.0 | 20.5±2.0 | 178±2.0 |

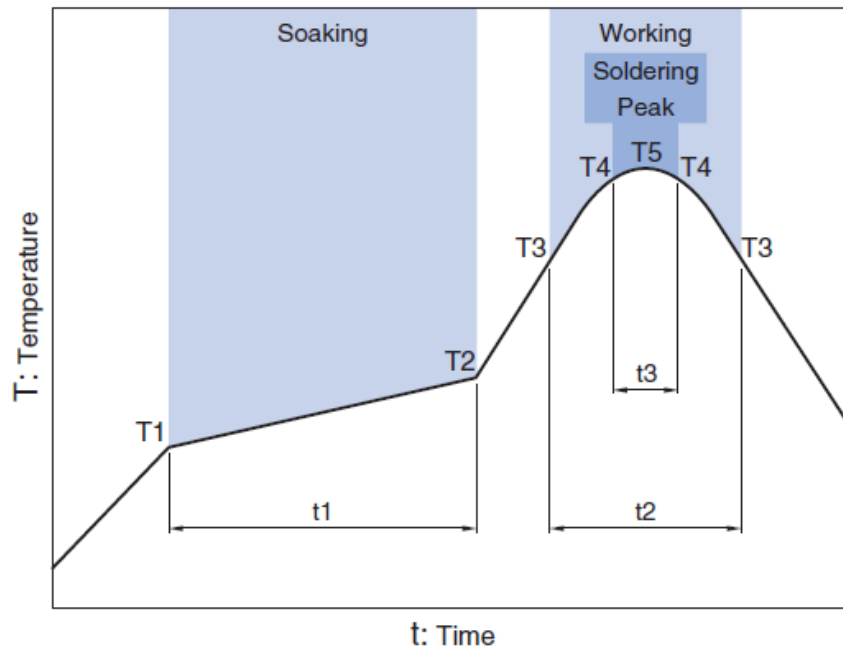
Taping Specification



| Packaging | Type | A | B | W | E | F | G | H | T | ϕD | P |
|------------|------|-----------|-----------|-----------|-----------|----------|----------|----------|-----------|---------------------|--------|
| Paper Type | 8060 | 6.30±0.20 | 8.30±0.20 | 16.0±0.20 | 1.75±0.10 | 7.5±0.05 | 4.0±0.10 | 2.0±0.05 | 0.30±0.10 | 1.50 +0.10 -0 | 12±0.1 |

Recommended Reflow Profile

Pb free solder



| Soaking | | | Working | | Soldering | | Peak |
|---------|-------|--------------|---------|-----------------|--------------|--------------|------------|
| Temp. | | Time | Temp. | Time | Temp. | Time | Temp. |
| T1 | T2 | t1 | T3 | t2 | T4 | t3 | T5 |
| 150°C | 180°C | 60 to 120sec | 230°C | more than 30sec | 247 to 253°C | within 10sec | 260°C Max. |

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